



**INTERFLUX**®  
ELECTRONICS



# LMPA-Q7

Low melting point solder paste



100% recyclable packaging system



Lower soldering T° (190°C-210°C)



No need for nitrogen

Very low voiding

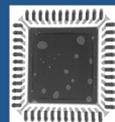
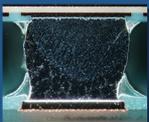


Suitable for Pin-in-Paste

High reliability



No-clean, absolutely halide free



[interflux.com](http://interflux.com)

[lmpa-q.com](http://lmpa-q.com)

